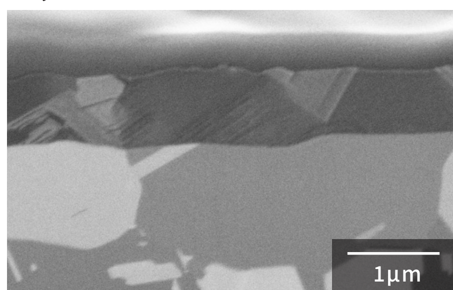
銅上の無電解銀めっき液
Electroless Ag Plating Process on Cu

トップシルベACC
TOP SILVE ACC

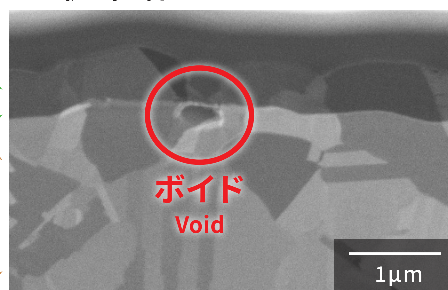
- 銅素材上に無電解銀めっきが直接でき、ナノ銀焼結接合用の下地として使用可能
  Can make electroless silver plating directly on copper substrates, can use as undercoat for silver sintering and bonding process
- 下地銅の腐食が少ない
  Can reduce corrosion on base copper
- 密着性およびファインパターン性に優れる
  Great adhesion, fine pattern ability

下地の腐食が少ない Can reduce corrosion on base copper

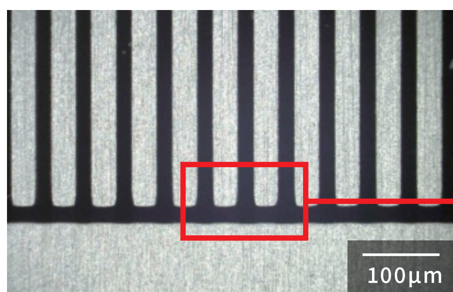
トップシルベACC TOP SILVE ACC



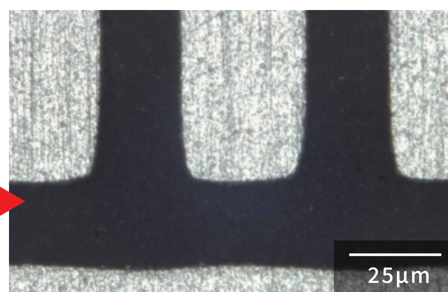
従来浴 Conventional bath



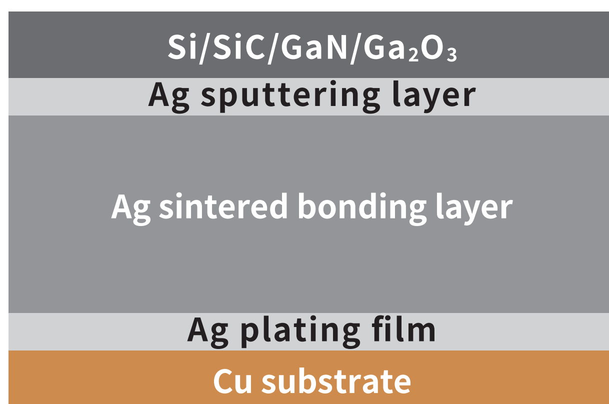
密着性およびファインパターン性に優れる Great adhesion, fine pattern ability



テープ剥離試験後
Tape peel test



ナノ銀焼結接合用途 For silver sintering and bonding process



析出性に優れる Excellent in deposition rate